有关敝公司产品的注意事项

请务必在使用敝公司产品之前阅读。

⚠ 注 意

产品目录中的记载内容

本产品目录中所记载的内容为2023年3月的内容。因产品改良等原因，可能会不经预告而变更其记载内容，或是停止供应本产品目录中所记载的产品。所以，请务必在使用前先确认最新的产品信息。

未按照本产品目录中所记载的内容或交货规格说明书使用敝公司产品的，即便其致使用设备发生损害、不良情况等时，敝公司也不承担任何责任，敬请知悉。

签署交货规格说明书

就本产品目录中所记载产品的产品规格等相关内容，敝公司备有交货规格说明书，详情请向敝公司咨询。在使用敝公司产品前请务必就交货规格说明书之内容确认并批准之。

实装前的事前评估

使用敝公司产品时，请务必事先安装到使用设备之后，在实际使用的环境下进行评估和确认。

用途的限定

1. 可以使用的设备

本产品目录中所记载的产品预设为使用于一般民用电子设备［音像设备、办公自动化设备、家电产品、办公设备、信息通讯设备（手机、电脑等）］以及面向本产品目录或是交货规格说明书中另行注明的设备或是敝公司另行承诺的设备的通用性，标准性用途。另外，面向下述设备的应用，敝公司也备有预设的产品系列，请参考本产品目录或是交货规格说明书的内容，使用相对应的产品。

用途	产品系列		品质等级(注释3)
	对象设备(注释1)	规格号（型号标记(注释2)）	
车载	汽车用电子设备（控制系 / 安全系）	A	1
	汽车用电子设备（车身系 / 情报系）	C	2
工业	通信基础设备·工业设备	B	2
医疗	医疗设备（国际（GHTF）第三类）	M	2
	医疗设备（国际（GHTF）第一类、第二类）	L	3
民用	一般电子设备	S	3
	移动设备专用(注释4)	E	4

注释1：基于敝公司所认知的该类设备对于电子元器件所需的一般要求规格，对于该产品系列进行的应用推荐。在讨论将各个产品系列使用在对象设备以外的设备上时，请务必事先向敝公司咨询。

注释2：在产品型号中左起第2位标注有上表中所记载的“规格号”。对于相关的详细内容，请参照有关各产品型号标示法的说明资料。

注释3：在各产品系列中，都设定了从上至下1至4的“品质等级”。另外，在未得到敝公司的事前书面承诺之前，请勿将敝公司的产品使用于相对于该产品的品质等级被设定为上位品质等级的设备。

注释4：本产品系列仅可应用于一般民用电子设备中的移动设备（智能手机、平板电脑、智能手表、掌上游戏机等）。由于其设计、规格和使用环境与面向“一般电子设备”的产品系列（规格号：S）不同，有关本产品系列的详细信息请参照交货规格说明书。另外，面向“一般电子设备”的产品系列（规格号：S）也可以应用于移动设备。

▶由于篇幅有限，本产品目录中只记载了有代表性的产品规格，若考虑使用敝公司产品时，请确认交货规格说明书中的详细规格。另外，有关各产品的详细信息(特性图、可靠性信息、使用时的注意事项等)，请参阅敝公司网站(http://www.ty-top.com/)。

2. 需要另行确认的设备

若考虑将本产品目录中所记载的产品使用于当产品发生故障、品质不良，或是由此引起的运转失常而可能会危及生命、身体或是财产，以及有可能给社会造成深刻影响的以下设备（不包括本产品目录或是交货规格说明书中另行注明可以使用设备）等时，请务必事先向敝公司咨询。

(1) 运输用设备（汽车驱动控制设备、火车控制设备、船舶控制设备等）
(2) 交通信号设备
(3) 防灾 / 保安设备
(4) 医疗设备（国际（GHTF）第三类）
(5) 高公共性信息通讯设备 / 信息处理设备（电话交换机、电话 / 无线 / 广播电视基站等）
(6) 其他与上述设备有同等品质与可靠性要求的设备

3. 禁止使用的设备

请勿将敝公司产品使用于对安全性和可靠性有着极高要求的以下设备。

(1) 航天设备（人工卫星、火箭等）
(2) 航空设备(注释1)
(3) 医疗设备（国际（GHTF）第四类）、植体（体内植入型）医疗设备(注释2)
(4) 发电控制设备（面向核能 / 水力 / 火力发电厂等的设备）
(5) 海底设备（海底中继设备、海中的作业设备等）
(6) 军事设备
(7) 其他与上述设备有同等品质与可靠性要求的设备

注释1：仅限于对航空设备的安全运行不产生直接干扰的设备［机内娱乐设备、机内照明设备、电动座椅、餐饮设备等］，在满足敝公司另行指定的相关条件时，亦可将敝公司产品用于以上用途。在贵公司考虑将敝公司的产品用于以上用途时，请务必事先向敝公司咨询相关的信息。

注释2：包括注入人体内的部分和与此相连接的体外部分。

4. 责任的限制

未经敝公司的事先书面同意，把本产品目录中所记载的产品使用于非敝公司预设用途的设备、前述需要向敝公司咨询的设备或敝公司禁止使用的设备，从而给客户或第三方造成损害的，敝公司不承担任何责任，敬请知悉。

安全设计

需将敝公司的产品使用于对安全性和可靠性要求较高的设备、电路上时，请进行充分的安全性评估和可靠性评估。另外，请通过设置保护电路、保护装置的系统，设置冗余电路不会被单一故障影响安全性的系统等失效导向安全（fail-safe）设计，确保充分的安全性。

有关知识产权

本产品目录中所记载的信息是用于说明相关产品的典型操作以及相关应用。此类信息的使用不代表对于敝公司以及第三方的知识产权以及其他权利的使用许可或是不侵权保证。

保证范围

敝公司产品的保证范围仅限于符合交货规格说明书中所记载的产品规格且已经交付的敝公司产品本身，由敝公司产品的故障或不良情况所诱发的损害，敝公司不承担任何责任，敬请知悉。但是，仅限于敝公司的产品作为通用性，标准性用途使用于本产品目录或是交货规格说明书中另行注明的设备，且以书面形式另行签署了交易基本合同书，品质保证协定书等时，敝公司将根据该合同等的条件提供保证。

正规销售渠道

本产品目录中所记载的内容适用于从敝公司营业所、销售子公司、销售代理店（即“正规销售渠道”）购买的敝公司产品，并不适用于从其他渠道购买的敝公司产品，敬请知悉。

出口时的注意事项

本产品目录中所记载的部分产品在出口时须事先确认《外汇和对外贸易法》以及美国在出口管理方面的相关法规，并办理相关手续。如有不明之处，请向敝公司咨询。

▶由于篇幅有限，本产品目录中只记载了有代表性的产品规格，若考虑使用敝公司产品时，请确认交货规格说明书中的详细规格。
另外，有关各产品的详细信息(特性图、可靠性信息、使用时的注意事项等)，请参阅敝公司网站(http://www.ty-top.com/)。

医疗设备用途使用指引

敝公司对于医疗设备国际（GHTF）第一类、第二类、第三类，都准备了相应的产品系列（左起第二位的产品型号的记号为“M”或是“L”）。因此，有意在医疗设备中采用敝公司产品时，请务必事先确认医疗设备的国际分类，并使用相应的产品系列。
另外，敝公司并没有准备意图使用于被分类为医疗设备国际（GHTF）第四类的所有设备，以及被分类为医疗设备国际（GHTF）第三类的植体（体内植入型）医疗设备（骨导式助听器、人工网膜系统、或是连接人体之体外装置等），因此请不要将敝公司的产品使用于上述任何设备中。如有不明之处，请与敝公司取得联系。

对于人体的风险		低 → 高			
日本	依照医药品医疗机器等法之分类(GHTF)	**第一类** 一般医疗设备 (GHTF Class A)	**第二类** 管制医疗设备 (GHTF Class B)	**第三类** 高度管制医疗设备 (GHTF Class C)	**第四类** 高度管制医疗设备 (GHTF Class D)
		认于发生不良情况时，对于人体产生风险的程度极低者。	认于发生不良情况时，对于人体产生风险的程度较低者。	认于发生不良情况时，对于人体产生风险的程度较高者。	对患者的侵入性高，于发生不良情况时，可能直接危及生命危险者。
		【代表实例】 ・体外诊断用仪器 ・喷雾器 ・血液气体分析器 ・脉波计 ・呼吸传感器 ・电动手术台 ・手术用照明装置 ・胆固醇分析仪 ・血型分析仪　　等	【代表实例】 ・电子体温计 ・电子血压计 ・电子内视镜 ・补聴器 ・心电仪 ・核磁共振成像(MRI) ・超音波诊断装置 ・成像诊断装置 ・X射线诊断装置 ・中央监护仪 ・血氧仪　　等	【代表实例】 ・透析机器 ・放射线治疗机器 ・输液泵 ・人工呼吸器 ・血糖监测系统 ・自动体外心脏除颤器(AED) ・皮肤激光扫描仪 ・手术电刀 ・胰岛素泵　　等	【代表实例】 ・植入式心脏起搏器 ・摄像软式血管镜 ・植入式输液泵 ・心脏用手术电刀 ・附心导管之检查装置 ・除颤器　　等
美国	FDA分类	**Class Ⅰ** General Controls	**Class Ⅱ** General Controls and Special Controls	**Class Ⅲ** General Controls and Premarket Approval	
		以医疗设备发生缺陷或故障之情况下，对病患或使用者也不会产生重大伤害或危害为前提之医疗机器。	可预设当医疗设备发生缺陷或故障时，对病患或使用者可能会造成伤害或产生危害之医疗机器。	可预设当医疗设备发生缺陷或故障时，对病患或使用者可能会产生严重伤害，致残或是致死之医疗机器。	
中国	医疗器械监督管理条例中的分类	**第一类**	**第二类**	**第三类**	
		风险程度低，实行常规管理可以保证其安全、有效的医疗器械。	具有中度风险，需要严格控制管理以保证其安全、有效的医疗器械。	具有较高风险，需要采取特别措施严格控制管理以保证其安全、有效的医疗器械。	
产品系列的对应状况		**面向医疗设备（国际（GHTF）第一类、第二类）的产品系列** （左起第二位的产品型号的记号：“L”）		**面向医疗设备（国际（GHTF）第三类）的产品系列** （左起第二位的产品型号的记号：“M”） ※注释	未对应

※注释：即使被分类为国际分类（GHTF）第三类，植体等部分的医疗设备也仍未对应。

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医疗设备（国际（GHTF）第一类、第二类）用途
绕线型金属系功率电感器 MCOIL™ LLEN 系列

系列前的记号来自型号，用来区分产品的种类和特性等。

回流焊

*使用温度范围：-40～+125℃（包含产品本身发热）

■型号标示法

L L E N	C	2 0 1 6	K K	T	1 R 0	M	
①	②	③	④	⑤	⑥	⑦	⑧

①系列

代码 ⑴⑵⑶⑷	
LLEN	医疗设备（国际（GHTF）第一类、第二类）用途 绕线型金属系功率电感器

(1) 产品群

代码	
L	电感器

(2) 范畴

代码	推荐设备	品质等级
L	医疗设备（国际（GHTF）第一类、第二类）	3

(3) 类型

代码	
E	绕线型金属系 高充填型

(4) 特效 / 特性

代码	
N	一般功率扼流

②特征

代码	特征
C	底面电极（树脂银×镀锡）

③尺寸（L×W）

代码	尺寸（L×W）[mm]
2016	2.0×1.6
2520	2.5×2.0

④尺寸（T）

代码	尺寸（T）[mm]
KK	1.0

⑤包装

代码	包装
T	卷盘带装

⑥标称电感值

代码（例）	标称电感值 [μH]
R47	0.47
1R0	1.0
4R7	4.7

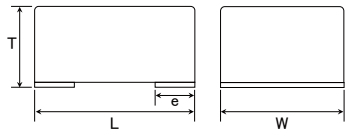
※R＝小数点

⑦电感量公差

代码	电感量公差
M	±20%

⑧管理记号

■标准外型尺寸 / 标准数量

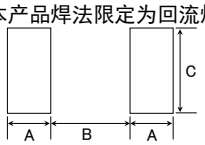


推荐焊盘图案

实装上的注意

・请确认实装状态后使用。

・本产品焊法限定为回流焊法。



Type	A	B	C
2016	0.7	0.8	1.8
2520	0.9	1.0	2.2

单位：mm

Type	L	W	T	e	标准数量 [pcs] 卷盘带装
2016KK	2.0±0.2 (0.079±0.008)	1.6±0.2 (0.063±0.008)	1.0 max (0.039 max)	0.5±0.3 (0.020±0.012)	3000
2520KK	2.5±0.2 (0.098±0.008)	2.0±0.2 (0.079±0.008)	1.0 max (0.039 max)	0.65±0.3 (0.026±0.012)	3000

单位：mm（inch）

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■PART NUMBER

●2016KK type 【Thickness : 1.0mm max.】

New part number	Old part number (for reference)	EHS	Nominal inductance [μH]	Inductance tolerance	Self-resonant frequency [MHz] (min.)	DC Resistance [Ω] (max.)	Rated current ※) [mA] (max.)		Measuring frequency [MHz]
							Saturation current Idc1	Temperature rise current Idc2	
LLENC2016KKTR47M	MEKK2016TR47M	RoHS	0.47	±20%	–	0.030	4,500	4,300	1
LLENC2016KKTR68M	MEKK2016TR68M	RoHS	0.68	±20%	–	0.052	3,800	3,300	1
LLENC2016KKT1R0M	MEKK2016T1R0M	RoHS	1.0	±20%	–	0.060	3,600	3,100	1
LLENC2016KKT2R2M	MEKK2016T2R2M	RoHS	2.2	±20%	–	0.150	2,400	1,900	1

●2520KK type 【Thickness : 1.0mm max.】

New part number	Old part number (for reference)	EHS	Nominal inductance [μH]	Inductance tolerance	Self-resonant frequency [MHz] (min.)	DC Resistance [Ω] (max.)	Rated current ※) [mA] (max.)		Measuring frequency [MHz]
							Saturation current Idc1	Temperature rise current Idc2	
LLENC2520KKTR33M	MEKK2520TR33M	RoHS	0.33	±20%	–	0.022	6,400	5,100	1
LLENC2520KKTR47M	MEKK2520TR47M	RoHS	0.47	±20%	–	0.025	5,900	4,800	1
LLENC2520KKT1R0M	MEKK2520T1R0M	RoHS	1.0	±20%	–	0.053	4,300	3,300	1
LLENC2520KKT1R5M	MEKK2520T1R5M	RoHS	1.5	±20%	–	0.069	3,200	2,800	1
LLENC2520KKT2R2M	MEKK2520T2R2M	RoHS	2.2	±20%	–	0.097	3,100	2,400	1
LLENC2520KKT4R7M	MEKK2520T4R7M	RoHS	4.7	±20%	–	0.240	1,600	1,500	1

※) The saturation current value (Idc1) is the DC current value having inductance decrease down to 30%. (at 20℃)
※) The temperature rise current value (Idc2) is the DC current value having temperature increase up to 40℃. (at 20℃)
※) The rated current is the DC current value that satisfies both of current value saturation current value and temperature rise current value.
※) Idc2 Measurement board data
Material:FR4
Board dimensions : 100 × 50 × 1.6t mm
Pattern dimensions : 45 × 45 mm (Double side board)
Pattern thickness : 70 μm

▸ This catalog contains the typical specification only due to the limitation of space. When you consider the purchase of our products, please check our specification.
For details of each product (characteristics graph, reliability information, precautions for use, and so on), see our Web site (http://www.ty-top.com/) .

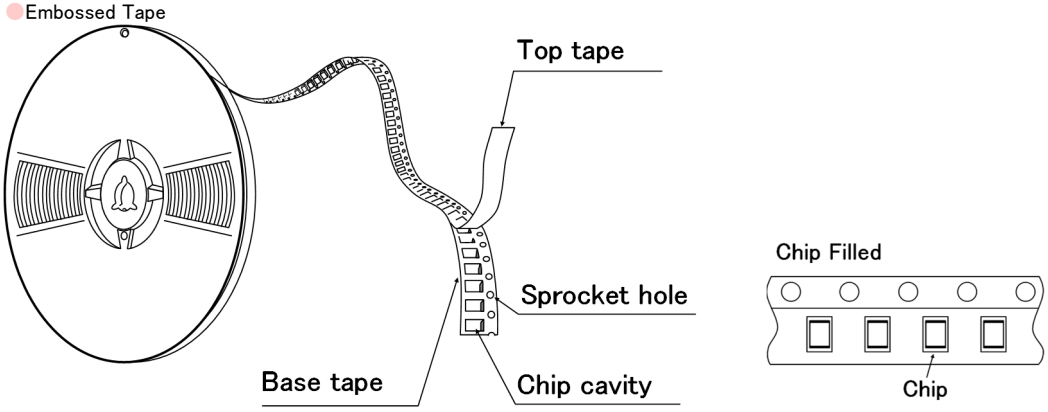
■PACKAGING

①Minimum Quantity

Type	Standard Quantity [pcs]
	Tape & Reel
2012HK	3000
2012KK	3000
2016MK	3000
2016HK	3000
2016KK	3000
2520KK	3000
2520MK	3000
3225HK	3000

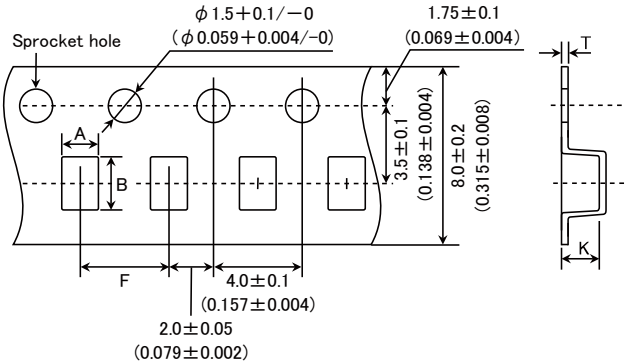
②Tape Material

●Embossed Tape



③Taping dimensions

●Embossed tape 8mm wide (0.315 inches wide)

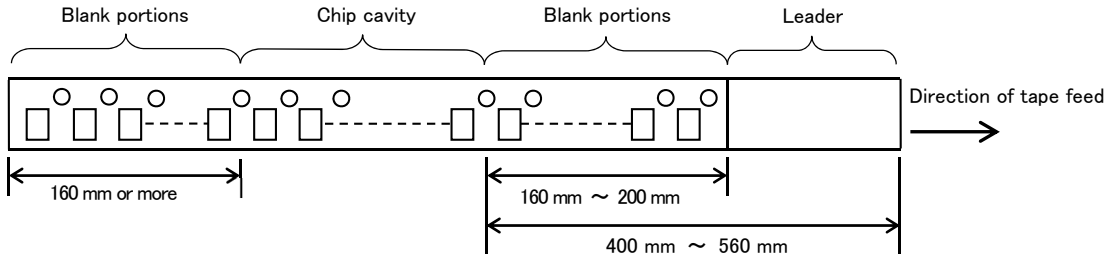


Type	Chip cavity		Insertion pitch	Tape thickness	
	A	B	F	T	K
2012HK	1.45±0.1 (0.057±0.004)	2.25±0.1 (0.089±0.004)	4.0±0.1 (0.157±0.004)	0.25±0.05 (0.009±0.002)	0.9+0.15/−0.1 (0.035+0.006/−0.004)
2012KK	1.45±0.1 (0.057±0.004)	2.25±0.1 (0.089±0.004)	4.0±0.1 (0.157±0.004)	0.25±0.05 (0.009±0.002)	1.1±0.1 (0.043±0.004)
2016MK	1.9±0.1 (0.075±0.004)	2.45±0.1 (0.097±0.004)	4.0±0.1 (0.157±0.004)	0.25±0.05 (0.009±0.002)	1.4±0.1 (0.055±0.004)
2016HK	1.9±0.1 (0.075±0.004)	2.45±0.1 (0.097±0.004)	4.0±0.1 (0.157±0.004)	0.25±0.05 (0.009±0.002)	1.2±0.1 (0.047±0.004)
2016KK	1.9±0.1 (0.075±0.004)	2.45±0.1 (0.097±0.004)	4.0±0.1 (0.157±0.004)	0.25±0.05 (0.009±0.002)	1.2±0.1 (0.047±0.004)

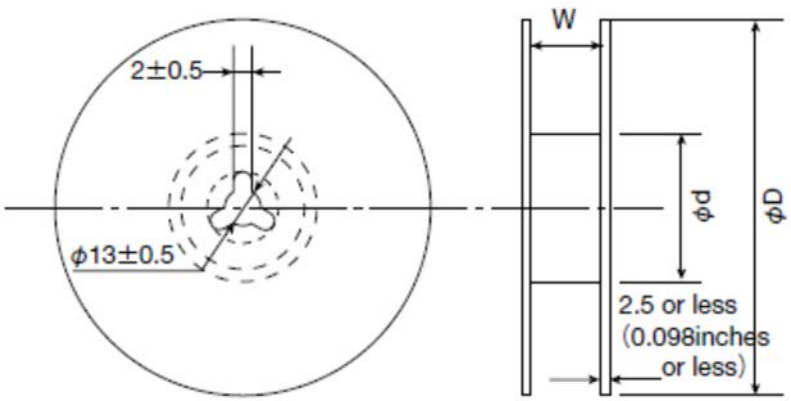
Type	Chip cavity		Insertion pitch	Tape thickness	
	A	B	F	T	K
2520KK	2.4±0.1 (0.094±0.004)	2.9±0.1 (0.114±0.004)	4.0±0.1 (0.157±0.004)	0.25±0.05 (0.009±0.002)	1.1±0.1 (0.043±0.004)
2520MK	2.4±0.1 (0.094±0.004)	2.9±0.1 (0.114±0.004)	4.0±0.1 (0.157±0.004)	0.25±0.05 (0.009±0.002	1.4±0.1 (0.055±0.004)
3225HK	2.8±0.1 (0.110±0.004)	3.5±0.1 (0.138±0.004)	4.0±0.1 (0.157±0.004)	0.25±0.05 (0.009±0.002	1.1±0.1 (0.043±0.004)

Unit : mm (inch)

④Leader and Blank portion



⑤Reel size

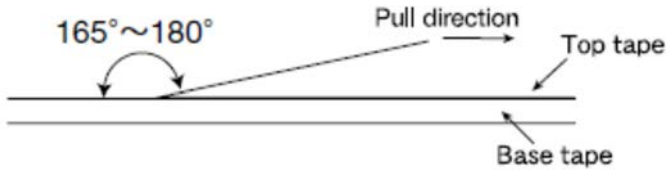


Type	Reel size (Reference values)		
	ϕD	ϕd	W
2012HK	180+0/−3 (7.087+0/−0.118)	60+1/−0 (2.36+0.039/0)	10.0±1.5 (0.394±0.059)
2012KK			
2016MK			
2016HK			
2016KK			
2520KK			
2520MK			
3225HK			

Unit : mm (inch)

⑥Top Tape Strength

The top The top tape requires a peel-off force of 0.1 to 1.0N in the direction of the arrow as illustrated below.



▸ This catalog contains the typical specification only due to the limitation of space. When you consider the purchase of our products, please check our specification.
For details of each product (characteristics graph, reliability information, precautions for use, and so on), see our Web site (http://www.ty-top.com/) .

Wire-wound Metal Power Inductors MCOIL™ LSEN series for General Electronic Equipment for Consumer
Wire-wound Metal Power Inductors MCOIL™ LSEP series for General Electronic Equipment for Consumer
Wire-wound Metal Power Inductors MCOIL™ LLEN series for Medical Devices classified as GHTF Classes A or B (Japan Classes I or II)
Wire-wound Metal Power Inductors MCOIL™ LLEP series for Medical Devices classified as GHTF Classes A or B (Japan Classes I or II)

■RELIABILITY DATA

1. Operating Temperature Range	
Specified Value	−40～＋125℃
Test Methods and Remarks	Including self-generated heat

2. Storage Temperature Range	
Specified Value	−40～＋85℃
Test Methods and Remarks	0 to 40℃ for the product with taping.

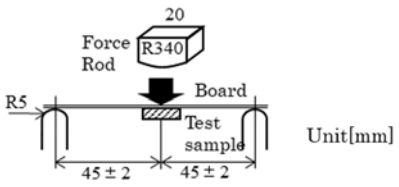
3. Rated current	
Specified Value	Within the specified tolerance

4. Inductance	
Specified Value	Within the specified tolerance
Test Methods and Remarks	Measuring equipment : LCR Meter (HP 4294A or equivalent) Measuring frequency : 1MHz、0.5V

5. DC Resistance	
Specified Value	Within the specified tolerance
Test Methods and Remarks	Measuring equipment : DC ohmmeter (HIOKI 3227 or equivalent)

6. Self resonance frequency	
Specified Value	—

7. Temperature characteristic	
Specified Value	Inductance change : Within ±15%
Test Methods and Remarks	Measurement of inductance shall be taken at temperature range within −40℃～＋125℃. With reference to inductance value at ＋20℃., change rate shall be calculated.

8. Resistance to flexure of substrate	
Specified Value	No damage
Test Methods and Remarks	The test samples shall be soldered to the test board by the reflow. As illustrated below, apply force in the direction of the arrow indicating until deflection of the test board reaches to 2 mm. Test board size : 100×40×1.0 mm Test board material : Glass epoxy-resin Solder cream thickness : 0.10 mm 

9. Insulation resistance : between wires	
Specified Value	—

10. Insulation resistance : between wire and over-coating	
Specified Value	—

11. Withstanding voltage : between wire and over-coating	
Specified Value	—

12. Adhesion of terminal electrode	
Specified Value	No abnormality.
Test Methods and Remarks	The test samples shall be soldered to the test board by the reflow. Applied force : 10N to X and Y directions. Duration : 5s. Solder cream thickness : 0.10mm

13. Resistance to vibration	
Specified Value	Inductance change : Within ±10% No significant abnormality in appearance.
Test Methods and Remarks	The test samples shall be soldered to the test board by the reflow. Then it shall be submitted to below test conditions.

Frequency Range	10～55Hz	
Total Amplitude	1.5mm (May not exceed acceleration 196m/s^2)	
Sweeping Method	10Hz to 55Hz to 10Hz for 1min.	
Time	X	For 2 hours on ach X, Y, and Z axis.
	Y	
	Z	

Recovery : At least 2hrs of recovery under the standard condition after the test, followed by the measurement within 48hrs.

14. Solderability	
Specified Value	At least 90% of surface of terminal electrode is covered by new solder.
Test Methods and Remarks	The test samples shall be dipped in flux, and then immersed in molten solder as shown in below table. Flux : Ethanol solution containing rosin 25%.

Solder Temperature	245±5℃
Time	5±0.5 sec.

※Immersion depth : All sides of mounting terminal shall be immersed.

15. Resistance to soldering heat	
Specified Value	Inductance change : Within ±10% No significant abnormality in appearance.
Test Methods and Remarks	The test sample shall be exposed to reflow oven at 230℃ for 40 seconds, with peak temperature at 260+0/−5℃ for 5 seconds, 2 times. Test board material : Glass epoxy-resin Test board thickness : 1.6mm Recovery : At least 2hrs of recovery under the standard condition after the test, followed by the measurement within 48hrs.

16. Thermal shock	
Specified Value	Inductance change : Within ±10% No significant abnormality in appearance.
Test Methods and Remarks	The test samples shall be soldered to the test board by the reflow. The test samples shall be placed at specified temperature for specified time by step 1 to step 4 as shown in below table in sequence. The temperature cycle shall be repeated 100 cycles.

Conditions of 1 cycle		
Step	Temperature (℃)	Duration (min)
1	−40±3	30±3
2	Room temperature	Within 3
3	+85±2	30±3
4	Room temperature	Within 3

Recovery : At least 2hrs of recovery under the standard condition after the test, followed by the measurement within 48hrs.

17. Damp heat	
Specified Value	Inductance change : Within ±10% No significant abnormality in appearance.
Test Methods and Remarks	The test samples shall be soldered to the test board by the reflow. The test samples shall be placed in thermostatic oven set at specified temperature and humidity as shown in below table. Temperature: 60±2℃ Humidity: 90～95%RH Time: 500+24/−0 hour Recovery : At least 2hrs of recovery under the standard condition after the test, followed by the measurement within 48hrs.

18. Loading under damp heat	
Specified Value	Inductance change : Within ±10% No significant abnormality in appearance.
Test Methods and Remarks	The test samples shall be soldered to the test board by the reflow. The test samples shall be placed in thermostatic oven set at specified temperature and humidity and applied the rated current continuously as shown in below table. Temperature: 60±2℃ Humidity: 90～95%RH Applied current: Rated current Time: 500+24/−0 hour Recovery : At least 2hrs of recovery under the standard condition after the test, followed by the measurement within 48hrs.

19. Low temperature life test	
Specified Value	Inductance change : Within ±10% No significant abnormality in appearance.
Test Methods and Remarks	The test samples shall be soldered to the test board by the reflow. After that, the test samples shall be placed at test conditions as shown in below table. Temperature: −40±2℃ Time: 500+24/−0 hour Recovery : At least 2hrs of recovery under the standard condition after the test, followed by the measurement within 48hrs.

20. High temperature life test	
Specified Value	Inductance change : Within ±10% No significant abnormality in appearance.
Test Methods and Remarks	The test samples shall be soldered to the test board by the reflow. After that, the test samples shall be placed at test conditions as shown in below table. Temperature: 125±2℃ Time: 500+24/−0 hour Recovery : At least 2hrs of recovery under the standard condition after the test, followed by the measurement within 48hrs.

21. Loading at high temperature life test	
Specified Value	—

22. Standard condition	
Specified Value	Standard test condition : Unless otherwise specified, temperature is 20±15℃ and 65±20%of relative humidity. When there is any question concerning measurement result: In order to provide correlation data, the test shall be condition of 20±2℃ of temperature, 65±5% relative humidity. Inductance is in accordance with our measured value.

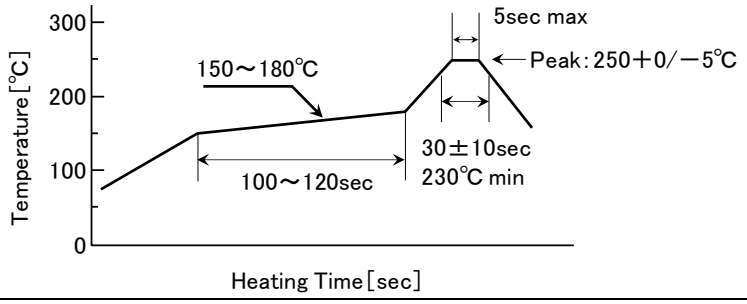
Wire-wound Metal Power Inductors MCOIL™ LSEN/LLEN/LCEN/LBEN/LMEN series
Wire-wound Metal Power Inductors MCOIL™ LSEP/LLEP series
Wire-wound Metal Power Inductors MCOIL™ LSEU/LLEU series

■PRECAUTIONS

1. Circuit Design	
Precautions	◆Verification of operating environment, electrical rating and performance 1. A malfunction in medical equipment, spacecraft, nuclear reactors, etc. may cause serious harm to human life or have severe social ramifications. As such, any inductors to be used in such equipment may require higher safety and/or reliability considerations and should be clearly differentiated from components used in general purpose applications. 2. When inductors are used in places where dew condensation develops and/or where corrosive gas such as hydrogen sulfide, sulfurous acid, or chlorine exists in the air, characteristic deterioration may occur. Please do not use inductors under such environmental conditions. ◆Operating Current (Verification of Rated current) 1. The operating current including inrush current for inductors must always be lower than their rated values. 2. Do not apply current in excess of the rated value because the inductance may be reduced due to the magnetic saturation effect. ◆Temperature rise Temperature rise of power choke coil depends on the installation condition in end products. Make sure that temperature rise of power choke coils in actual end products is within the specified temperature range.

2. PCB Design	
Precautions	◆Land pattern design 1. Please refer to a recommended land pattern.
Technical considerations	◆Land pattern design Surface Mounting ・ Mounting and soldering conditions should be checked beforehand. ・ Applicable soldering process to this products is reflow soldering only.

3. Considerations for automatic placement	
Precautions	◆Adjustment of mounting machine 1. Excessive impact load should not be imposed on the products when mounting onto the PC boards. 2. Mounting and soldering conditions should be checked beforehand.
Technical considerations	◆Adjustment of mounting machine 1. When installing products, care should be taken not to apply distortion stress as it may deform the products.

4. Soldering	
Precautions	◆Reflow soldering 1. Please contact any of our offices for a reflow soldering, and refer to the recommended condition specified. 2. The product shall be used reflow soldering only. 3. Please do not add any stress to a product until it returns in normal temperature after reflow soldering. ◆Lead free soldering 1. When using products with lead free soldering, we request to use them after confirming adhesion, temperature of resistance to soldering heat, soldering etc sufficiently.
Technical considerations	◆Reflow soldering 1. If products are used beyond the range of the recommended conditions, heat stresses may deform the products, and consequently degrade the reliability of the products. Recommended reflow condition (Pb free solder) 

5. Cleaning	
Precautions	◆Cleaning conditions 1. Washing by supersonic waves shall be avoided.
Technical considerations	◆Cleaning conditions 1. If washed by supersonic waves, the products might be broken.

6. Handling	
Precautions	◆Handling 1. Keep the product away from all magnets and magnetic objects. ◆Breakaway PC boards (splitting along perforations) 1. When splitting the PC board after mounting product, care should be taken not to give any stresses of deflection or twisting to the board. 2. Board separation should not be done manually, but by using the appropriate devices. ◆Mechanical considerations 1. Please do not give the product any excessive mechanical shocks. 2. Please do not add any shock and power to a product in transportation. ◆Pick-up pressure 1. Please do not push to add any pressure to a winding part. Please do not give any shock and push into a ferrite core exposure part. ◆Packing 1. Please avoid accumulation of a packing box as much as possible.
Technical considerations	◆Handling 1. There is a case that a characteristic varies with magnetic influence. ◆Breakaway PC boards (splitting along perforations) 1. The position of the product on PCBs shall be carefully considered to minimize the stress caused from splitting of the PCBs. ◆Mechanical considerations 1. There is a case to be damaged by a mechanical shock. 2. There is a case to be broken by the handling in transportation. ◆Pick-up pressure 1. Damage and a characteristic can vary with an excessive shock or stress. ◆Packing 1. If packing boxes are accumulated, that could cause a deformation on packing tapes or a damage on the products.

7. Storage conditions	
Precautions	◆Storage 1. To maintain the solderability of terminal electrodes and to keep the packing material in good condition, temperature and humidity in the storage area should be controlled. ・ Storage conditions Ambient temperature : 0～40℃ Humidity : Below 70% RH ・ The recommended ambient temperature is below 30℃. Even under ideal storage conditions, solderability of products electrodes may decrease as time passes. For this reason, product should be used within 6 months from the time of delivery. In case of storage over 6 months, solderability shall be checked before actual usage.
Technical considerations	◆Storage 1. Under a high temperature and humidity environment, problems such as reduced solderability caused by oxidation of terminal electrodes and deterioration of taping/packaging materials may take place.